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## **N-Channel Power MOSFET**

30V, 73A, 8mΩ

#### **FEATURES**

- Low R<sub>DS(ON)</sub> to minimize conductive Losses
- Low gate charge for fast power switching
- 100% UIS and R<sub>q</sub> tested
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21 definition

PRODUCT SUMMARY						
PARAMETER		VALUE	UNIT			
$V_{ t DS}$		30	V			
R <sub>DS(on)</sub> (max)	$V_{GS} = 10V$	8	mΩ			
	$V_{GS} = 4.5V$	12.5				
$Q_{g}$		7.2	nC			





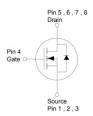


#### **APPLICATIONS**

- DC-DC Converters
- Battery Power Management
- ORing FET/Load Switch

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Notes: MSL 1 (Moisture Sensitivity Level) per J-STD-020

ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25°C unless otherwise noted)						
PARAMETER		SYMBOL	LIMIT	UNIT		
Drain-Source Voltage		$V_{DS}$	30	V		
Gate-Source Voltage		$V_{GS}$	±20	V		
Continuous Drain Current (Note 1)	$T_C = 25^{\circ}C$	l <sub>D</sub>	73	Α		
Continuous Drain Current	$T_A = 25^{\circ}C$		14			
Pulsed Drain Current (Note 1)		I <sub>DM</sub>	292	А		
Single Pulse Avalanche Current (Note 2)		I <sub>AS</sub>	23	Α		
Single Pulse Avalanche Energy (Note 2)		E <sub>AS</sub>	26	mJ		
Total Power Dissipation	$T_C = 25^{\circ}C$	P <sub>D</sub>	69	W		
Total Fower Dissipation	$T_C = 125$ °C		14			
Total Pawer Dissipation	$T_A = 25^{\circ}C$	P <sub>D</sub>	2.6	W		
Total Power Dissipation	$T_A = 125$ °C		0.5			
Operating Junction and Storage Temperature Range		$T_J,T_STG$	- 55 to +150	°C		

THERMAL RESISTANCE				
PARAMETER	SYMBOL	LIMIT	UNIT	
Thermal Resistance – Junction to Case	R <sub>eJC</sub>	1.8	°C/W	
Thermal Resistance – Junction to Ambient	R <sub>eJA</sub>	48	°C/W	

**Thermal Performance Note:**  $R_{\Theta JA}$  is the sum of the junction-to-case and case-to-ambient thermal resistances. The case-thermal reference is defined at the solder mounting surface of the drain pins.  $R_{\Theta JA}$  is guaranteed by design while  $R_{\Theta CA}$  is determined by the user's board design.

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#### **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C unless otherwise noted) **SYMBOL** MAX. **PARAMETER CONDITIONS** MIN. TYP. UNIT Static $V_{GS} = 0V$ , $I_D = 250 \mu A$ Drain-Source Breakdown Voltage $BV_{DSS}$ 30 ٧ $V_{GS} = V_{DS}, I_{D} = 250 \mu A$ 1 V Gate Threshold Voltage $V_{GS(TH)}$ 1.6 2.5 $V_{GS} = \pm 20V, V_{DS} = 0V$ Gate-Source Leakage Current ±100 $I_{GSS}$ nΑ $V_{GS}=0V,\;V_{DS}=30V$ 1 ----Drain-Source Leakage Current $I_{DSS}$ μΑ $V_{GS} = 10V, I_D = 14A$ 8 6.5 Drain-Source On-State Resistance mΩ R<sub>DS(on)</sub> (Note 3) $V_{GS} = 4.5V, I_D = 14A$ 9.5 12.5 Forward Transconductance (Note 3) $V_{DS} = 5V, I_{D} = 14A$ --S --30 $g_{\text{fs}} \\$ Dynamic (Note 4) $V_{GS} = 10V, V_{DS} = 15V,$ **Total Gate Charge** 14.4 $Q_g$ $I_D = 14A$ Total Gate Charge 7.2 $Q_g$ nC $V_{GS} = 4.5V, V_{DS} = 15V,$ Gate-Source Charge $Q_{gs}$ 2.6 $I_D = 14A$ Gate-Drain Charge $Q_{gd}$ 3.3 Input Capacitance $C_{iss}$ 843 $V_{GS} = 0V, V_{DS} = 15V,$ **Output Capacitance** $C_{\text{oss}}$ 157 рF -f = 1.0MHzReverse Transfer Capacitance 95 $C_{rss}$ f = 1.0MHz, open drain 0.9 3 Ω Gate Resistance $R_{\alpha}$ 6 Switching (Note 4) Turn-On Delay Time 4.8 $t_{d(on)}$ Rise Time 12.5 $t_{r}$ -- $V_{GS} = 10V, V_{DS} = 15V,$ ns $I_D=14A,\;R_G=3.3\Omega$ Turn-Off Delay Time 27.6 $t_{\text{d}(\text{off})}$ Fall Time $t_{\rm f}$ 8.2 **Source-Drain Diode** Diode Forward Voltage (Note 3) $V_{GS} = 0V, I_{S} = 15A$ $V_{SD}$ --1 ٧ Reverse Recovery Time --16 -ns $t_{rr}$ $I_{S} = 14A$ , Reverse Recovery Charge $Q_{rr}$ 8.3 nC $di/dt = 100A/\mu s$

#### Notes:

- 1. Current limited by package.
- 2. L = 0.1mH,  $V_{GS} = 10V$ ,  $V_{DS} = 25V$ ,  $R_G = 25\Omega$ ,  $I_{AS} = 23A$ , Starting  $T_J = 25^{\circ}C$
- 3. Pulse test: Pulse Width ≤ 300µs, duty cycle ≤ 2%.
- 4. Switching time is essentially independent of operating temperature.

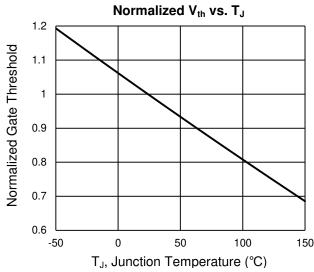
#### ORDERING INFORMATION

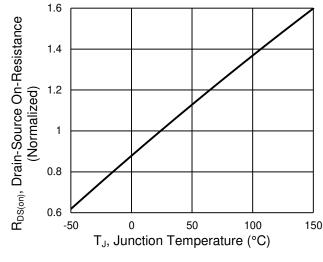
PART NO.	PACKAGE	PACKING
TSM080N03PQ56 RLG	PDFN56	2,500pcs / 13" Reel



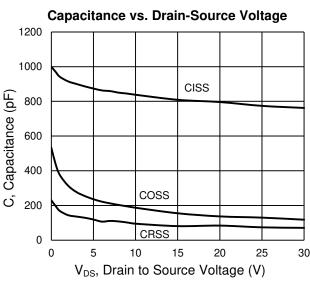
#### **CHARACTERISTICS CURVES**

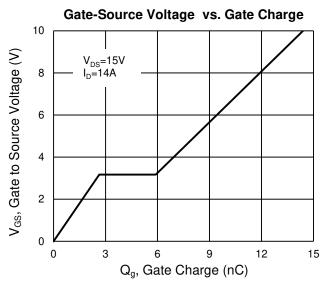
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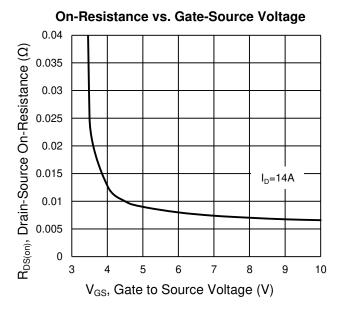


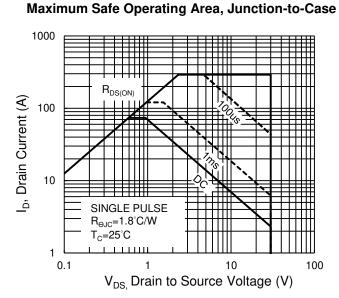


On-Resistance vs. Junction Temperature









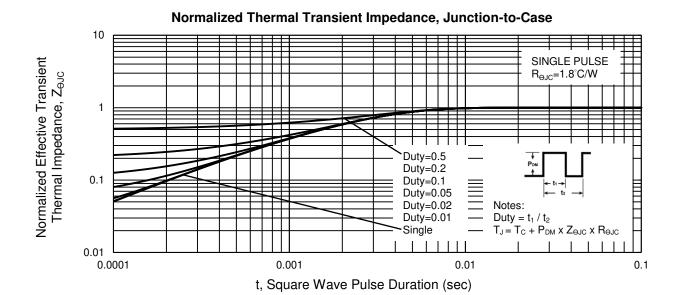
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#### **CHARACTERISTICS CURVES**

(T<sub>A</sub> = 25°C unless otherwise noted)



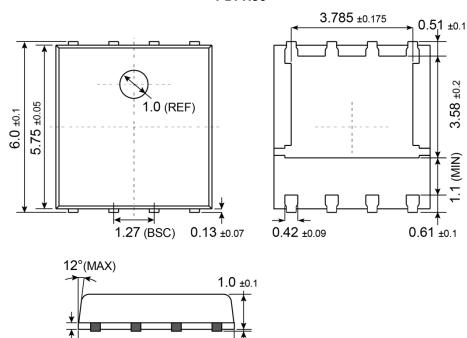
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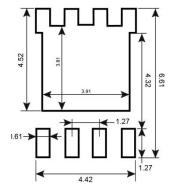
## PACKAGE OUTLINE DIMENSIONS (Unit: Millimeters)

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# SUGGESTED PAD LAYOUT (Unit: Millimeters)

0.25 ±0.05



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0.05 (MAX)

#### **MARKING DIAGRAM**



Y = Year Code

M = Month Code for Halogen Free Product

4.9 ±0.1

O =Jan P =Feb Q =Mar R =Apr

S =May T =Jun U =Jul V =Aug W =Sep X =Oct Y =Nov Z =Dec

L = Lot Code (1~9, A~Z)



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